

4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY
Product Summary

V _{BR} (Min)	I _{PP} (Max)	C _T (Typ)
6V	10A	1.0pF

Description

The DT2041-04SO is a high-performance device suitable for protecting four high speed I/Os. These devices are assembled in SOT26 package and have high ESD surge capability and low capacitance.


Applications

Typically used at high-speed ports such as USB 2.0, IEEE1394 (Firewire®, iLink), Serial ATA, DVI™, HDMI™, PCI.

Features

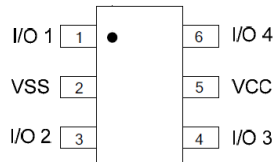
- Low Clamping Voltage: Typical 9V at 10A 100ns, TLP, I/O to V_{SS}; Typical 8V at 10A 100ns, TLP, V_{CC} to V_{SS}
- IEC 61000-4-2 (ESD): Air – ±30kV, Contact – ±30kV
- IEC61000-4-5(Lighting): 10A, I/O to V_{SS}; 12A, V_{CC} to V_{SS}
- TLP Dynamic Resistance: 0.25Ω
- Low Channel Input Capacitance of 1.0pF Typical
- 4 Channel of ESD Protection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**

Mechanical Data

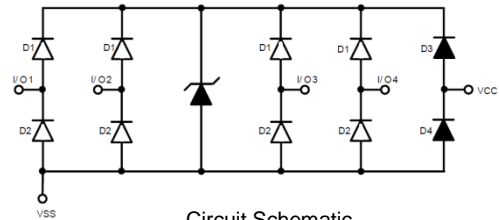
- Case: SOT26
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe (Lead Free Plating) Solderable per MIL-STD-202, Method208 
- Weight: 0.016 grams (Approximate)

SOT26


Top View



Device Schematic

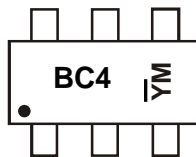
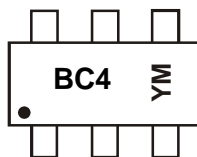


Circuit Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT2041-04SO-7	Standard	BC4	7	8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


BC4 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: D = 2016)
M = Month (ex: 9 = September)
Note: "—" Represents Internal Code

Date Code Key

Year	2016	2017	2018	2019	2020	2021
Code	D	E	F	G	H	I

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC61000-4-5	I _{PP}	±10	A	I/O to V _{SS} , 8/20 μs
Peak Pulse Current, per IEC61000-4-5	I _{PP}	±12	A	V _{CC} to V _{SS} , 8/20 μs
Peak Pulse Power, per IEC61000-4-5	P _{PP}	105	W	I/O to V _{SS} , 8/20 μs
Operating Voltage (DC)	V _{DC}	5.5	V	I/O to V _{SS} , V _{CC} to V _{SS}
ESD Protection – Contact Discharge, per IEC61000-4-2	V _{ESD_CONTACT}	±30	kV	I/O to V _{SS} , V _{CC} to V _{SS}
ESD Protection – Air Discharge, per IEC61000-4-2	V _{ESD_AIR}	±30	kV	I/O to V _{SS} , V _{CC} to V _{SS}
Operating Temperature	T _{OP}	-55 to +85	°C	—
Storage Temperature	T _{STG}	-55 to +150	°C	—

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P _D	300	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	R _{θJA}	417	°C/W

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V _{RWM}	—	—	5.5	V	I/O to V _{SS} , V _{CC} to V _{SS}
Reverse Current (Note 6)	I _R	—	—	1	μA	V _R = 5V, I/O to V _{SS} , V _{CC} to V _{SS}
Reverse Breakdown Voltage	V _{BR}	6	—	9	V	I _R = 1mA, I/O to V _{SS} , V _{CC} to V _{SS}
Forward Clamping Voltage	V _F	-1.0	-0.8	—	V	I _F = -15mA, I/O to V _{SS} , V _{CC} to V _{SS}
Holding Voltage	V _H	5.5	—	—	V	—
Trigger Voltage	V _{TRIG}	—	9	9.5	V	—
Reverse Clamping Voltage (Note 7)	V _{C_5A}	—	7.5	—	V	I _{PP} = 5A, I/O to V _{SS} , 8/20 μs
Reverse Clamping Voltage (Note 7)	V _{C_10A}	—	9	10.5	V	I _{PP} = 10A, I/O to V _{SS} , 8/20 μs
ESD Clamping Voltage	V _{ESD}	—	9	—	V	TLP, 10A, tp = 100ns, I/O to V _{SS}
		—	8	—		TLP, 10A, tp = 100ns, V _{CC} to V _{SS}
Dynamic Resistance	R _{DIF}	—	0.25	—	Ω	TLP, 10A, tp = 100ns, I/O to V _{SS}
		—	0.15	—		TLP, 10A, tp = 100ns, V _{CC} to V _{SS}
Channel Input Capacitance	C _T	—	1.0	1.5	pF	V _{I/O} = 2.5V, V _{CC} =5V, f = 1MHz
Variation of Channel Input Capacitance	ΔC _T	—	0.02	—	pF	V _{SS} = 0V, V _{I/O} = 2.5V, f = 1MHz, I/O_x to V _{SS} – I/O_y to V _{SS}

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - Short duration pulse test used to minimize self-heating effect.
 - Clamping voltage value is based on an 8x20μs peak pulse current (I_{PP}) waveform.

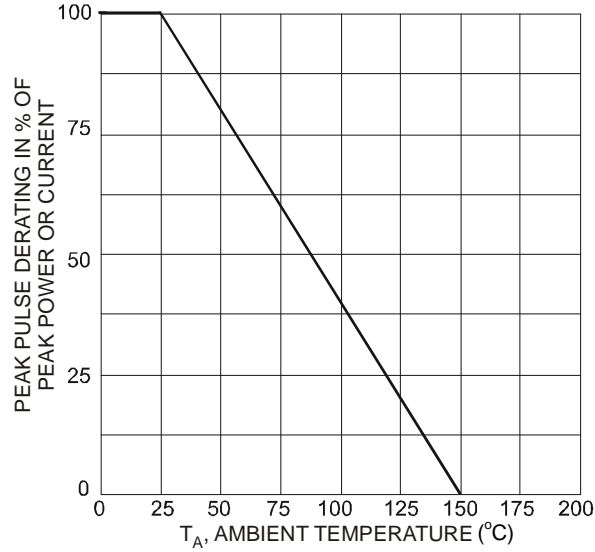


Figure 1 Pulse Derating Curve

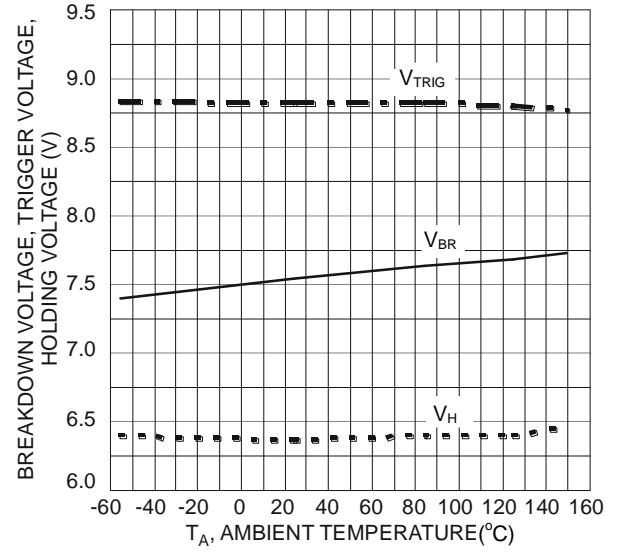


Figure 2 V_{BR} , Trigger Voltage, Holding Voltage vs. Ambient Temperature

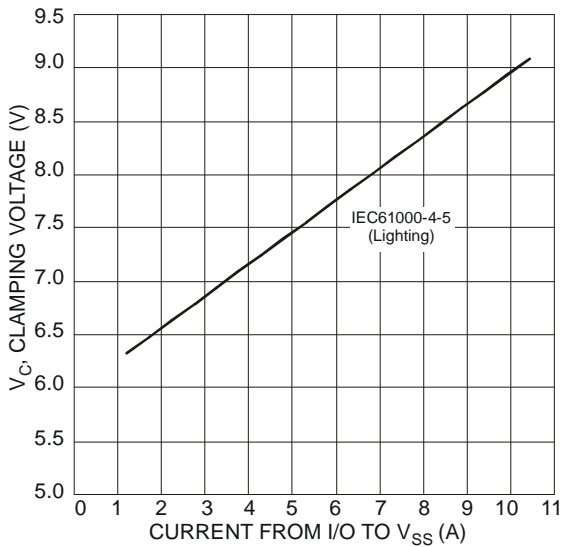


Figure 3 Clamping Voltage Characteristic

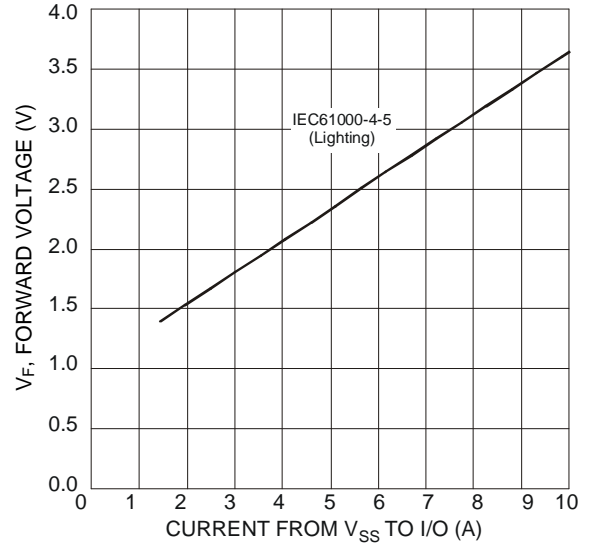


Figure 4 Forward Voltage Characteristic

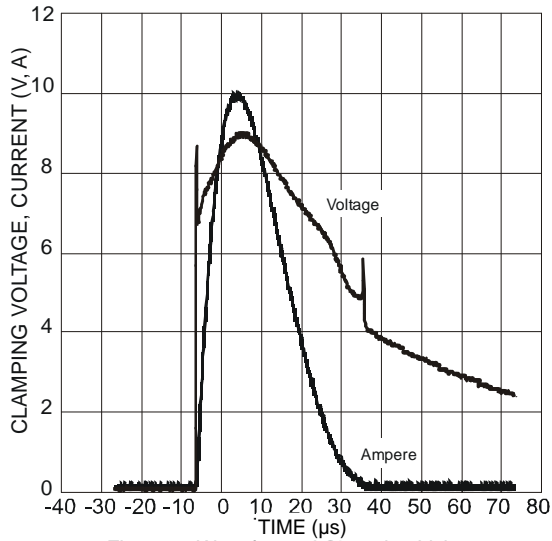


Figure 5 Waveform of Clamping Voltage, Current vs. Time (8/20 μ s, I/O to V_{SS})

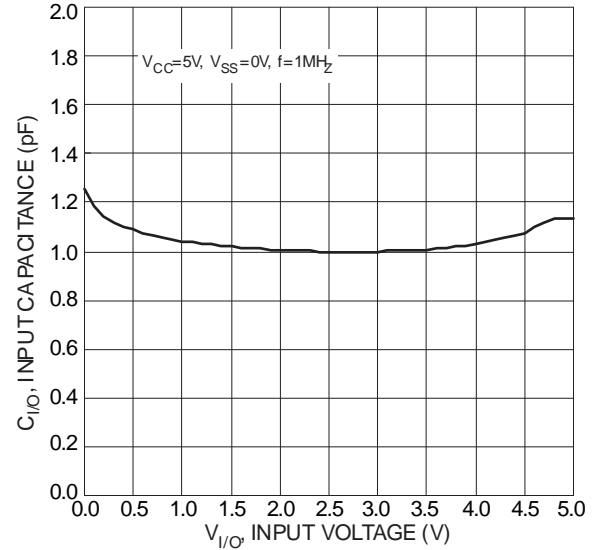


Figure 6 Input Capacitance vs. Input Voltage

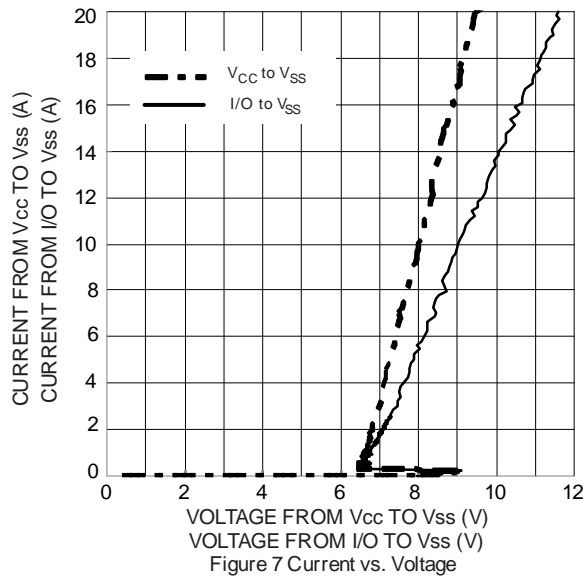
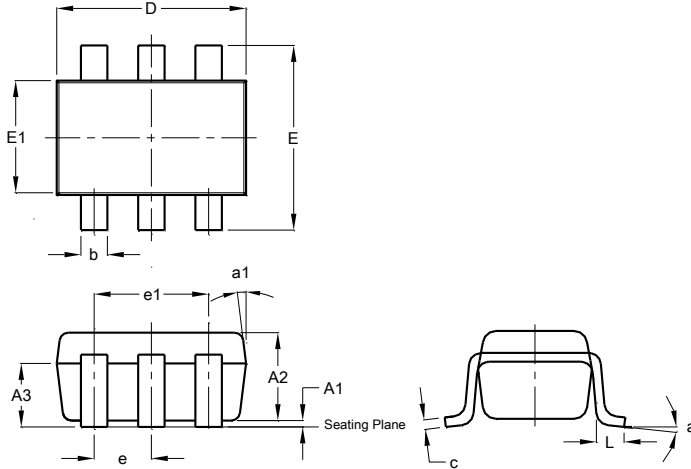


Figure 7 Current vs. Voltage

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26

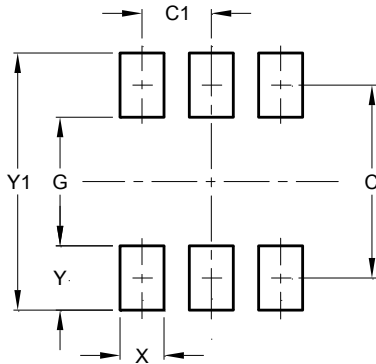


SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

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